




Gating a Quantum Dot through the Sequential Removal of Single Electrons from a Nanoscale Floating Gate

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We use the tip of an atomic force microscope (AFM) to charge floating metallic gates defined on the surface of a Si/SiGe heterostructure. The AFM tip serves as an ideal and movable cryogenic switch, allowing us to bias a floating gate to a specific voltage and then lock the charge on the gate by withdrawing the tip. Biasing with an AFM tip allows us to reduce the size of a quantum dot floating-gate electrode down to approximately 100 nm. Measurements of the conductance through a quantum dot formed beneath the floating gate indicate that its charge changes in discrete steps. From the statistics of the single-electron leakage events, we determine the floating-gate leakage resistance $R \sim 10^{19}$ Ohm—a value that is immeasurable by conventional means.

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Device



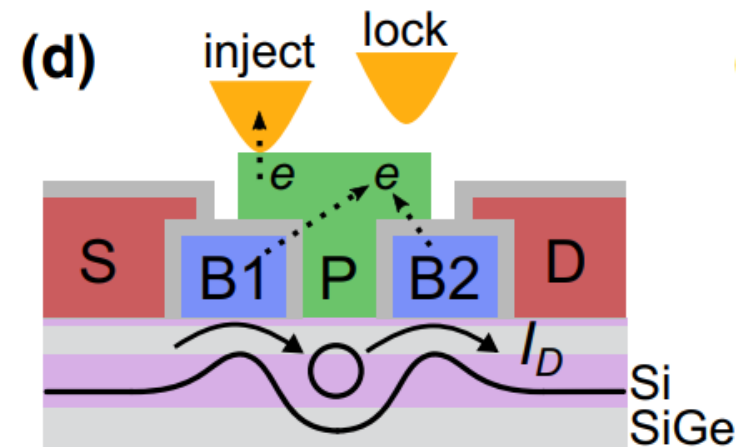
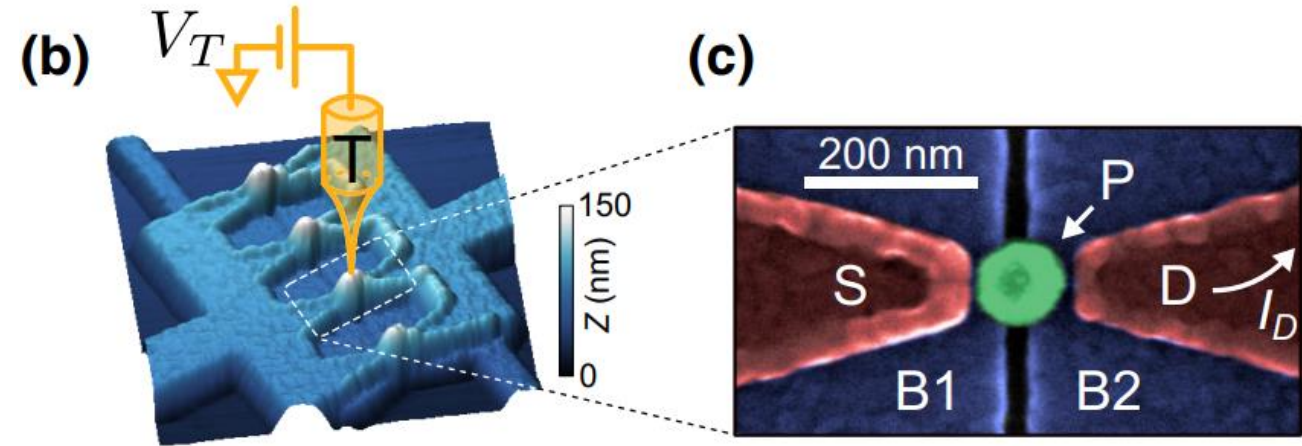
Motivation

- Problem: growing # RT control lines
- Solution: Sample-and-hold circuit (Charge floating gate)
 - Zero resistance switch
 - High electrical insulation
 - To date achieved only using FETs in: GaAs, Si/SiGe, CMOS QDs

Device:

- Accumulation-mode (undoped Si/SiGe heterostructure)
 - 2nm Si Cap
 - 50nm Si_{0.7}Ge_{0.3}
 - 5nm Si quantum well
- 3 Gate Layers:

Al barriers	B1,B2
Al accumulation	S,D
Pd plunger	P (good AFM tip contact)



Discharge floating gate

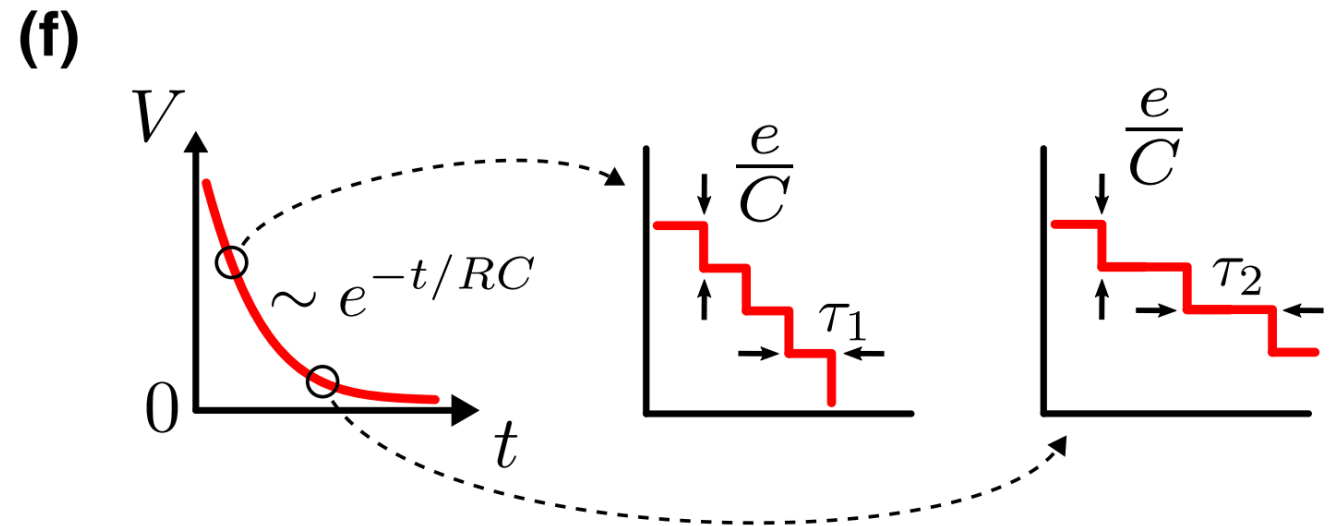
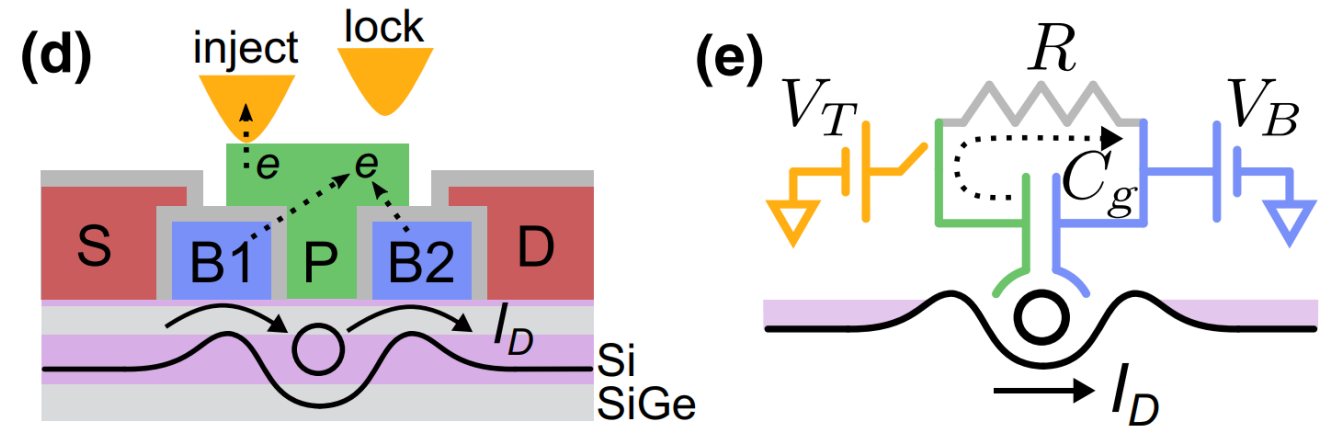


Floating gate discharge

Floating gate: Charged capacitor

Classical discharge: $V \sim e^{-t/RC}$
 \Rightarrow combined RC time

QM limit: discrete Steps (single e-tunnelling)
 $\Delta V = e/C$
 $\langle \Delta t \rangle = \tau$





Operation continuous vs lock



Contact mode:

Bias gate with AFM tip (regular gate)

Charge lock:

Retract biased tip (200nm)

Gate discharges over time

=> retraces CB peaks

Gate small => discrete discharging steps

1e tunnelling to B1(B2)

=> gate resolution limited to ~1mV

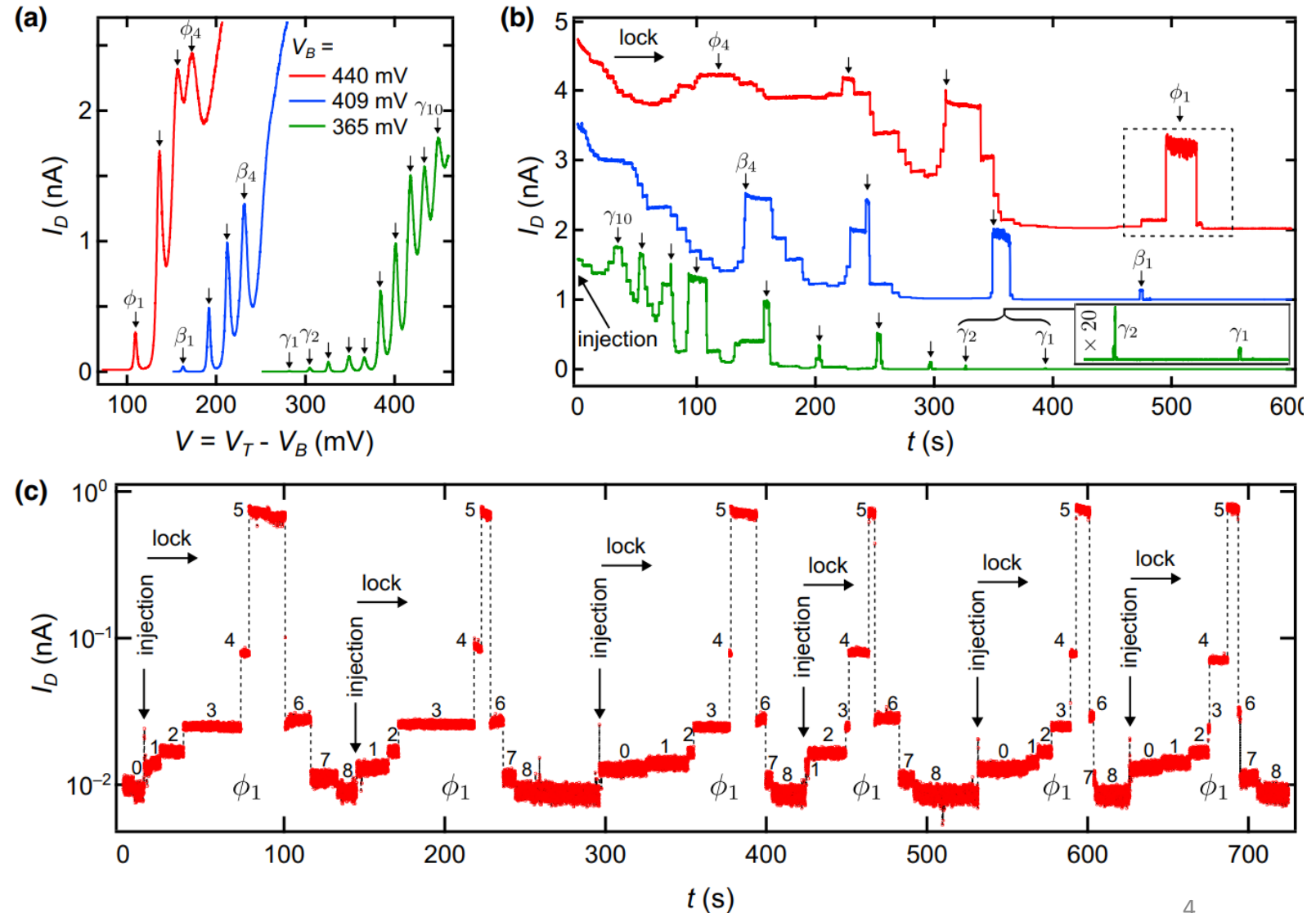
(few e QD: remove few 100e from gate)

Reproducibility (ϕ_1)

Same # discharging steps

(2 missing out of 50)

=> mostly single e⁻ tunnelling





Operation continuous vs lock



Contact mode vs charge lock:

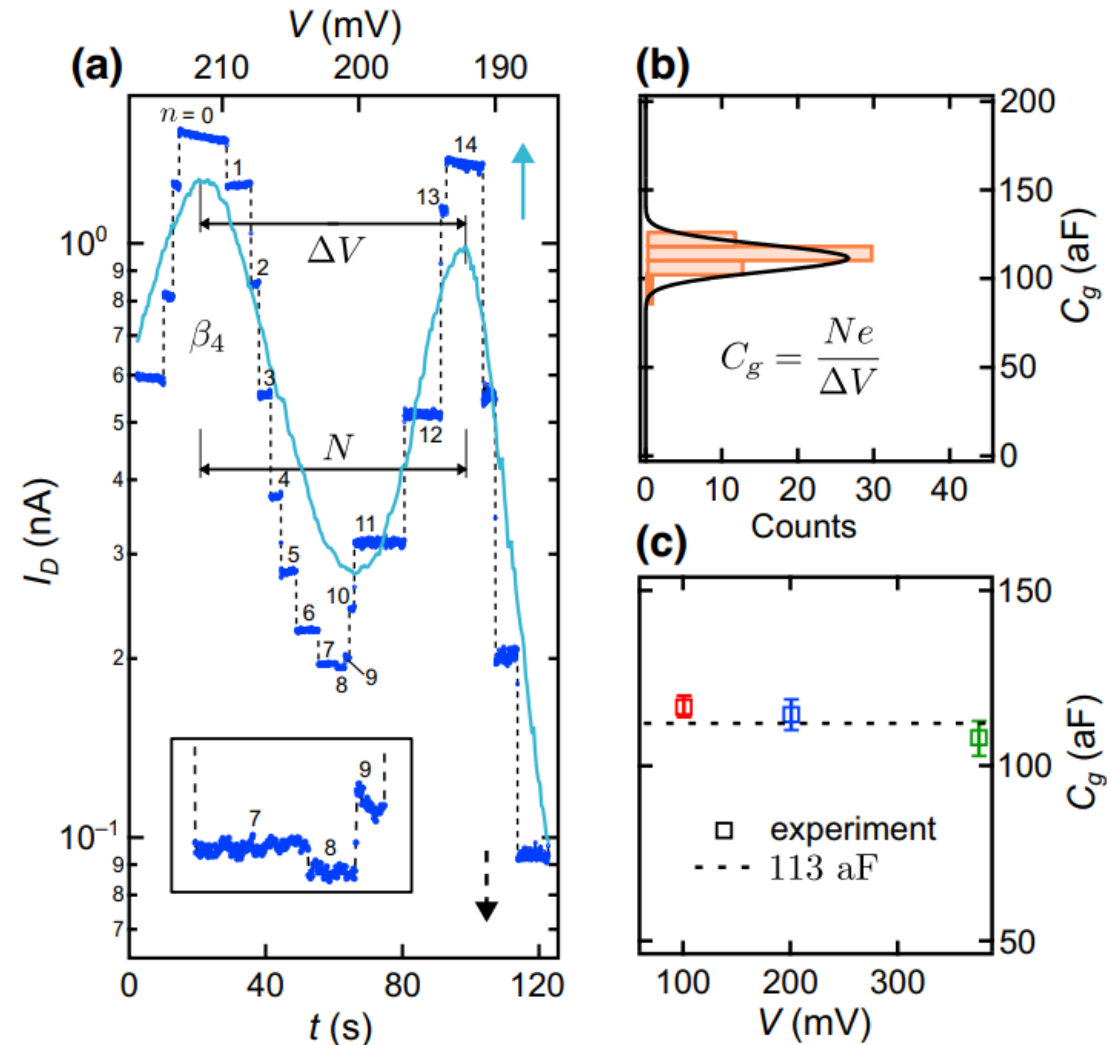
Bias gate with AFM tip (regular gate)

Smaller CB amplitude than charge lock

enhanced T_e due to AFM contact?

Capacitance of gate:

- $C_g = Ne/\Delta V$ (~14 electrons needed btw peaks)
=> $C_g \sim 112$ aF
($C_{gQD} \sim 10$ aF; 1 electron btw peaks added)
- C indep. V (gate geometry)
Slight drop: change of QD size
- 16'000 times larger capacitance precision than previous e-counting methods
- 1000 smaller footprint floating gates compared to FET
- $\Delta t = R \cdot C_{stray}$ (takes 1000 longer to measure same R wit FET)





Fano factor



Fano factor definition:

For a counting process after time t the Fano factor is:

$$P(t) = \frac{e^{-\frac{t}{\tau}}}{\tau} \Rightarrow \int_0^{\infty} P(t) dt = 1$$

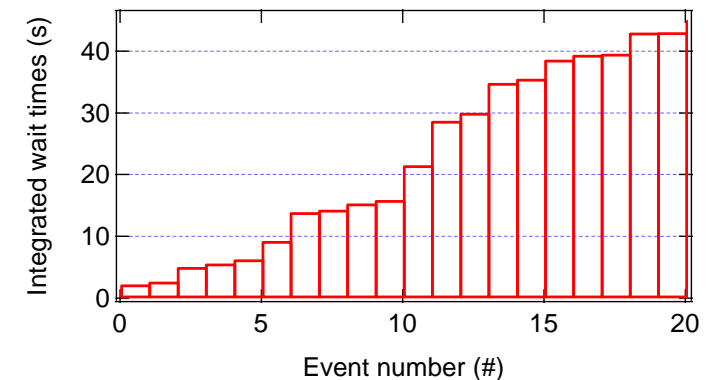
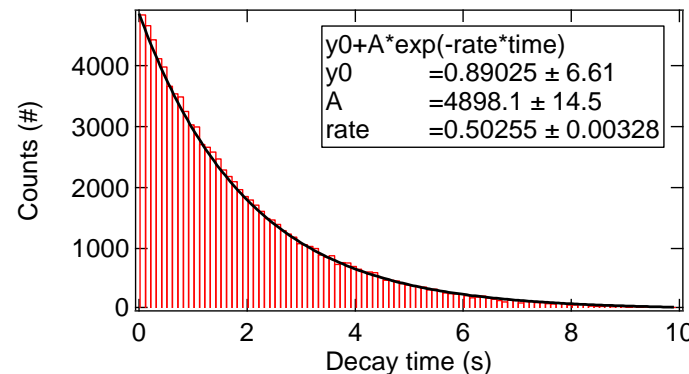
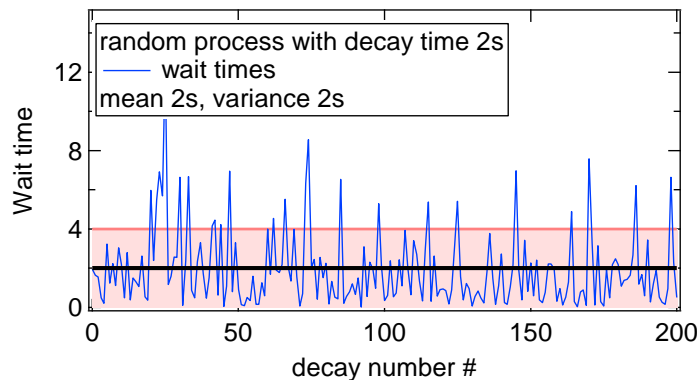
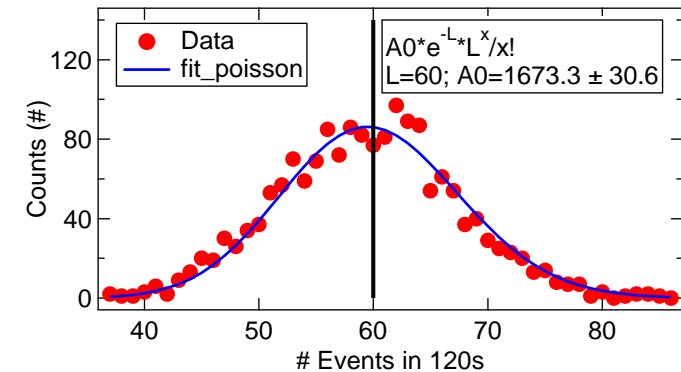
$$F(t) = \frac{\sigma_t^2}{\mu_t}$$

t : time
 σ_t^2 : variance
 μ_t : mean

- Likelihood of an event occurring in any time interval is equal for all time:
 => Holding times exponentially distributed (sigma = mean)
 => Poisson counting process (F=1; F=0 for constant function)

$$E = \int_0^{\infty} t \cdot P(t) dt = \tau$$

$$Var = \sqrt{\int_0^{\infty} (t - \tau)^2 \cdot P(t) dt} = \tau$$



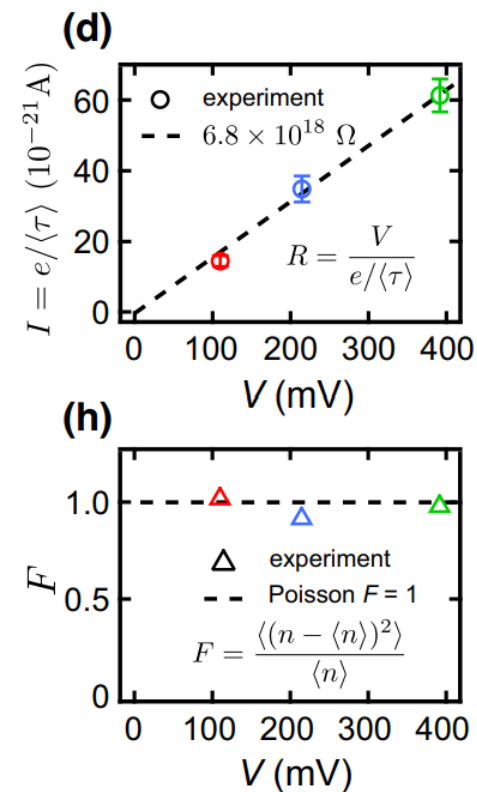
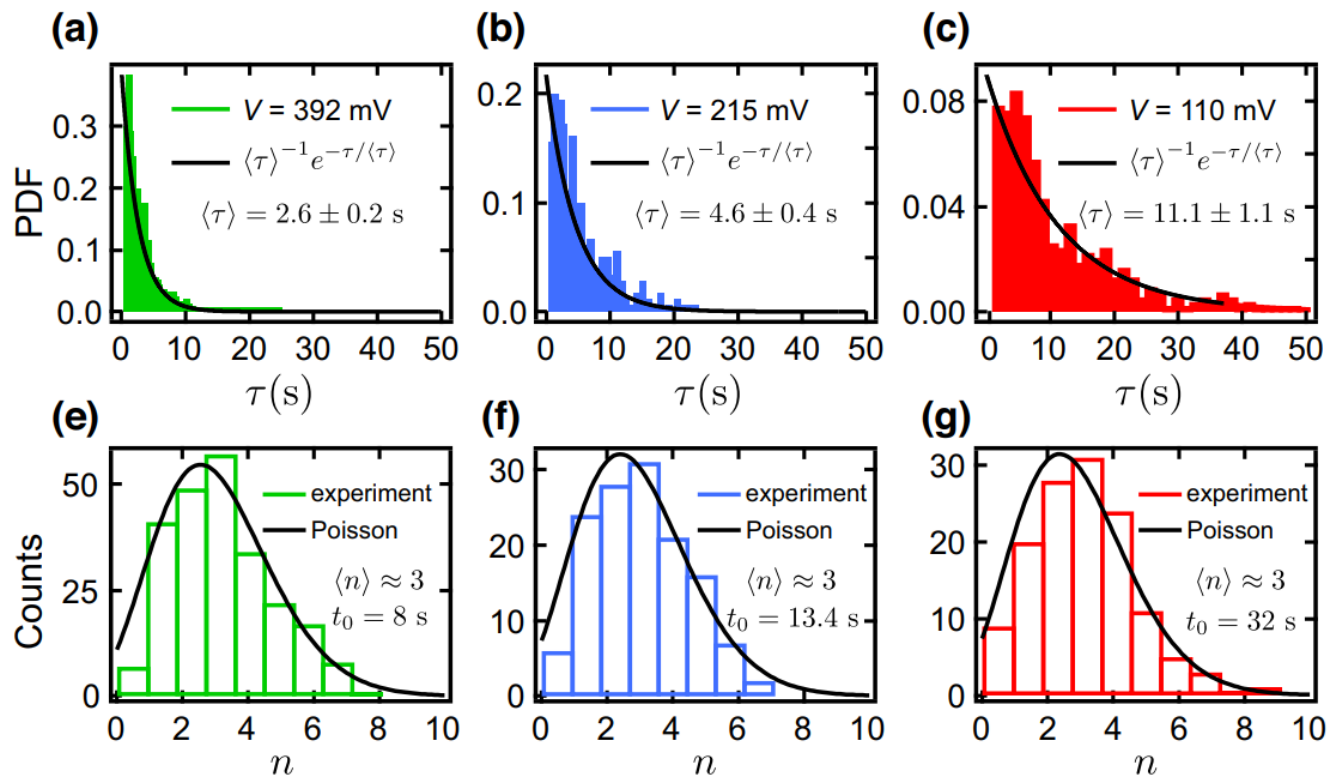


Tunnelling statistics



Uncorrelated electron tunneling

- Uncorrelated tunnelling: exponential waiting time distribution
 $I = V/R = e/\langle\tau\rangle \Rightarrow \langle\tau\rangle \sim \Delta V$
- Second moment expected to be poisson-distr. (Fano factor 1)

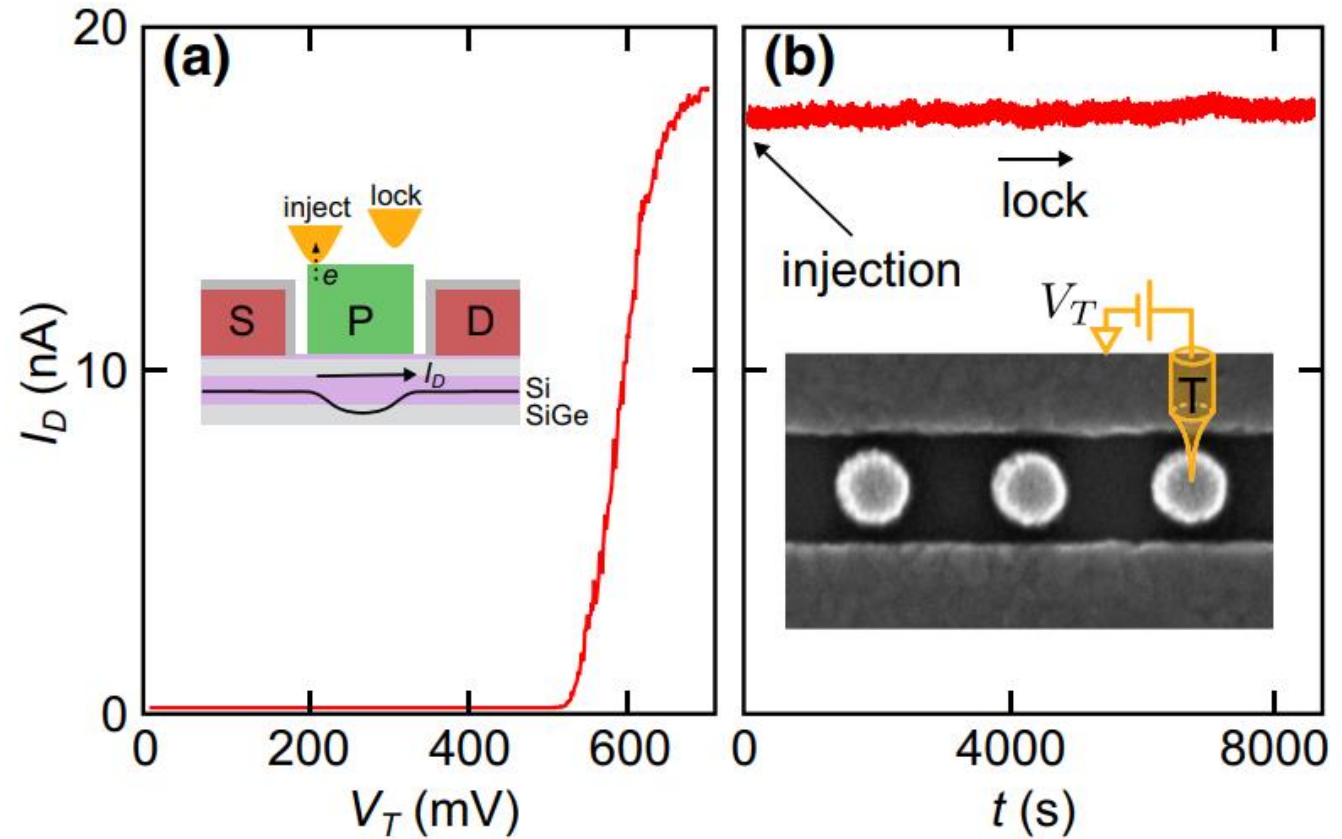


Single layer device



Device

- Single gate layer (S,D,P)
- No barriers
- Transistor like turn-on curve
- Floating gates sit directly on Si substrate
Substrate: only leakage path
- Charge retention:
Tens of e- leaking during hours
- Future: thicker oxide





Summary



- Gate locking demonstrated using AFM + floating gate
- Few 100s hold-time in QD device (interleaved gates)
- Hours hold-time in 1L device (transistor) without noticeable decay
- AFM allows for extremely small foot-print (100nm disc): 113aF, 200 electrons to accumulated dot
- Very large leakage resistance to barrier determined by counting statistics ($6,8e18$ Ohm)
- Counting statistics: Poisson process, Fano factor = 1